

# TIM-GAP HTC-11

*Cool it Right*

## DATA SHEET

Highly Conformable Thermally Conductive Gap Filler

### Descriptions

**TIM-GAP HTC-11** is a silicone putty type sheet interface material specially designed with high thermal Conductivity ( $11\text{W}/\text{m}^{\circ}\text{K}$ ) and total conformability with very low pressure. It offers very low compression force at high compression rate. Putty type nature greatly reduce contact resistance in small gaps and uneven mating surfaces

### Key Features

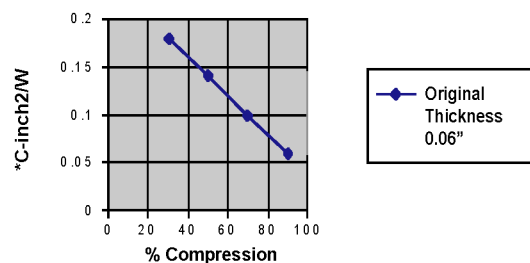
- High Thermal Conductivity ( $11\text{W}/\text{m}^{\circ}\text{K}$ )
- Electrically Insulating
- Smooth and highly compliant surface
- Clean and easy to apply
- High temperature resistance prevents dry out

### Applications

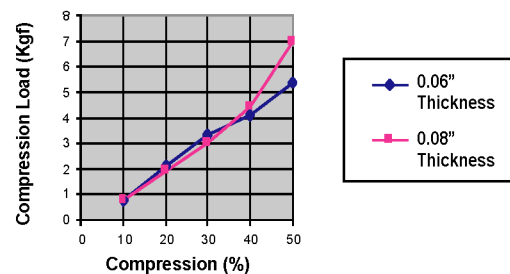
- Interface for discrete semiconductors requiring low pressure or spring clamp mounting
- CDROM Cooling
- Medical devices
- Between CPU and Heat Spreader
- Consumer electronics
- Industrial control

PHYSICAL PROPERTY	TEST METHOD	HTC-11
Type	Silicone	
Color	Visual	Gray
Operating Temp. range °C		-60 to 200
Thermal Conductivity, $\text{W}/\text{m}^{\circ}\text{k}$	ASTM D-5470 Modified	11
Breakdown Voltage	ASTM D-149	>6000
Volume Resistivity, Ohm-cm	ASTM D257	$10^{11}$
Available thickness, inch.		0.06, 0.08, 0.10

Compression vs Thermal Resistance



Compression Rate vs Load



### Availability

- **TIM-GAP HTC-11** is available in 300mm x 200mm sheets or die-cut parts. Materials are available standard and/or special shape and size.
- Tooling charges vary depending on tolerances and complexity of the part



**Disclaimer:** All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent